

SL-SMT 3.50/07/180G 1.5AU BK RL

Weidmüller Interface GmbH & Co. KG
 Klingenbergstraße 26
 D-32758 Detmold
 Germany

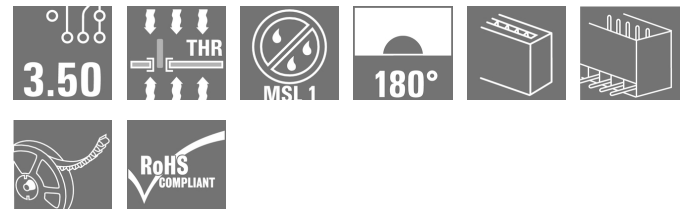
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Product image


Similar to illustration

High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**


General ordering data

| | |
|--------------|--|
| Version | PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number of poles: 7, 180°, Solder pin length (l): 1.5 mm, Gold-plated, black, Tape |
| Order No. | 1518990000 |
| Type | SL-SMT 3.50/07/180G 1.5AU BK RL |
| GTIN (EAN) | 4050118326635 |
| Qty. | 265 pc(s). |
| Product data | IEC: 320 V / 15 A UL: 300 V / 10 A |
| Packaging | Tape |

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Technical data

Dimensions and weights

| | | | |
|--------------------------|---------|-----------------|------------|
| Depth | 7.5 mm | Depth (inches) | 0.295 inch |
| Height | 12.6 mm | Height (inches) | 0.496 inch |
| Height of lowest version | 11.1 mm | Net weight | 2.645 g |
| Width | 25.9 mm | Width (inches) | 1.02 inch |

System specifications

| Product family | OMNIMATE Signal - series BL/SL 3.50 | Type of connection | Board connection |
|--|--|--|------------------|
| Mounting onto the PCB | THT/THR solder connection | Pitch in mm (P) | 3.5 mm |
| Pitch in inches (P) | 0.138 inch | Outgoing elbow | 180° |
| Number of poles | 7 | Number of solder pins per pole | 1 |
| Solder pin length (l) | 1.5 mm | Solder pin length tolerance | 0 / -0.3 mm |
| Solder pin dimensions | d = 1.2 mm, Octagonal | Solder pin dimensions = d tolerance | 0 / -0,03 mm |
| Solder eyelet hole diameter (D) | 1.4 mm | Solder eyelet hole diameter tolerance (D)+ | 0,1 mm |
| Outside diameter of solder pad | 2.3 mm | Template aperture diameter | 2.1 mm |
| L1 in mm | 21 mm | L1 in inches | 0.827 inch |
| Number of rows | 1 | Pin series quantity | 1 |
| Touch-safe protection acc. to DIN VDE 57 106 | Safe from back-of-hand touch | Touch-safe protection acc. to DIN VDE 0470 | IP 10 |
| Volume resistance | ≤5 mΩ | Can be coded | Yes |
| Plugging force/pole, max. | 6 N | Pulling force/pole, max. | 6 N |

Material data

| | | | |
|---------------------------------------|---|---------------------------------------|--------------------------------|
| Insulating material | LCP GF | Colour | black |
| Colour chart (similar) | RAL 9011 | Insulating material group | IIIa |
| Comparative Tracking Index (CTI) | ≥ 175 | Moisture Level (MSL) | 1 |
| UL 94 flammability rating | V-0 | Contact material | CuSn |
| Contact surface | Gold-plated | Layer structure of solder connection | 1...3 μm Ni / 2...4 μm Sn matt |
| Layer structure of plug contact | 1...3 μm Ni / 2...4 μm Sn / 1.7...2.3 μm Au | Storage temperature, min. | -40 °C |
| Storage temperature, max. | 70 °C | Operating temperature, min. | -50 °C |
| Operating temperature, max. | 100 °C | Temperature range, installation, min. | -30 °C |
| Temperature range, installation, max. | 100 °C | | |

Rated data acc. to IEC

| | | | |
|---|------------------------|---|--------|
| tested acc. to standard | IEC 60664-1, IEC 61984 | Rated current, min. number of poles (Tu=20°C) | 15 A |
| Rated current, max. number of poles (Tu=20°C) | 12 A | Rated current, min. number of poles (Tu=40°C) | 13 A |
| Rated current, max. number of poles (Tu=40°C) | 10 A | Rated voltage for surge voltage class / pollution degree II/2 | 320 V |
| Rated voltage for surge voltage class / pollution degree III/2 | 160 V | Rated voltage for surge voltage class / pollution degree III/3 | 160 V |
| Rated impulse voltage for surge voltage class/ pollution degree II/2 | 2.5 kV | Rated impulse voltage for surge voltage class/ pollution degree III/2 | 2.5 kV |
| Rated impulse voltage for surge voltage class/ contamination degree III/3 | 2.5 kV | | |

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Technical data

Rated data acc. to CSA

| | | | |
|-----------------------------------|-------|-----------------------------------|-------|
| Rated voltage (Use group B / CSA) | 300 V | Rated voltage (Use group D / CSA) | 300 V |
| Rated current (Use group B / CSA) | 10 A | Rated current (Use group D / CSA) | 10 A |

Rated data acc. to UL 1059

| | | | |
|---------------------------------------|---|---------------------------------------|--------|
| Institute (UR) |  | Certificate No. (UR) | E60693 |
| Rated voltage (Use group B / UL 1059) | 300 V | Rated voltage (Use group D / UL 1059) | 300 V |
| Rated current (Use group B / UL 1059) | 10 A | Rated current (Use group D / UL 1059) | 10 A |
| Reference to approval values | Specifications are maximum values, details - see approval certificate. | | |

Packing

| | | | |
|--|---------|--|-------------------------------|
| Packaging | Tape | VPE length | 60 mm |
| VPE width | 330 mm | VPE height | 330 mm |
| Tape depth (T2) | 16.5 mm | Tape width (W) | 44 mm |
| Tape pocket depth (K0) | 16 mm | Tape pocket height (A0) | 7.8 mm |
| Tape pocket width (B0) | 33.2 mm | Tape pocket separation (P1) | 16 mm |
| Tape hole separation (E) | 1.75 mm | Tape pocket separation (F) | 20.2 mm |
| Tape reel diameter \varnothing (A) | 330 mm | Surface resistance | $R_s = 10^9 - 10^{12} \Omega$ |
| Width Pick & Place Pad (W_{PPP}) | 6.8 mm | Length Pick & Place Pad (L_{PPP}) | 12.65 mm |
| Diameter of the withdrawal surface ($\varnothing D_{max}$) | 5 mm | Protrusion 1 Pick & Place Pad ($L_{01 (PPP)}$) | 2.5 mm |
| Protrusion 2 Pick & Place Pad ($P_{02 (PPP)}$) | 2.7 mm | | |

Classifications

| | | | |
|-------------|-------------|-------------|-------------|
| ETIM 6.0 | EC002637 | ETIM 7.0 | EC002637 |
| ECLASS 9.0 | 27-44-04-02 | ECLASS 9.1 | 27-44-04-02 |
| ECLASS 10.0 | 27-44-04-02 | ECLASS 11.0 | 27-46-02-01 |

Important note

| | |
|----------------|--|
| IPC conformity | Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request. |
| Notes | <ul style="list-style-type: none"> • Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet $D = 1.4 + 0.1 \text{ mm}$ • Solder eyelet diameter $D = 1.5 + 0.1 \text{ mm}$, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months |

Creation date March 24, 2021 4:22:09 AM CET

Catalogue status 12.03.2021 / We reserve the right to make technical changes.

Data sheet**SL-SMT 3.50/07/180G 1.5AU BK RL****Weidmüller Interface GmbH & Co. KG**
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Germanywww.weidmueller.com**Technical data****Approvals**

Approvals



| | |
|-----------------------|---------|
| ROHS | Conform |
| UL File Number Search | E60693 |

Downloads

| | |
|------------------|----------------------|
| Engineering Data | STEP |
|------------------|----------------------|

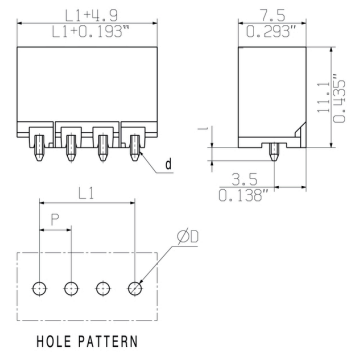
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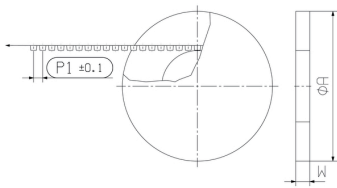
Drawings

Dimensional drawing

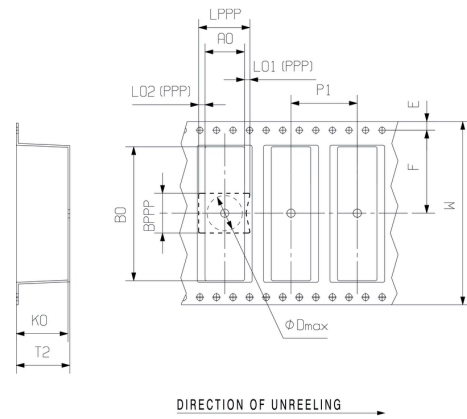


HOLE PATTERN

Dimensional drawing



Dimensional drawing



Example of use



Recommended wave soldering profiles

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 Germany
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 Fax: +49 5231 14-292083
 www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is ‚activated‘. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.